MN3111H

Vertical Driver LSI for Video Camera CCD Area Image Sensor

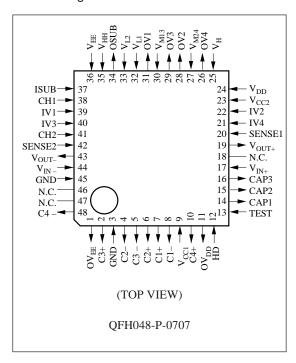
Overview

The MN3111H is a vertical driver LSI for a two-dimensional interline CCD image sensor. It features a built-in power supply circuit that, in conjunction with such external components as four booster capacitors, six voltage stabilization capacitors, eight Schottky barrier diodes, and two Zener diodes, produces stabilized +15.0V and -10.0V power supplies from a +5.0V input and HD pulses.

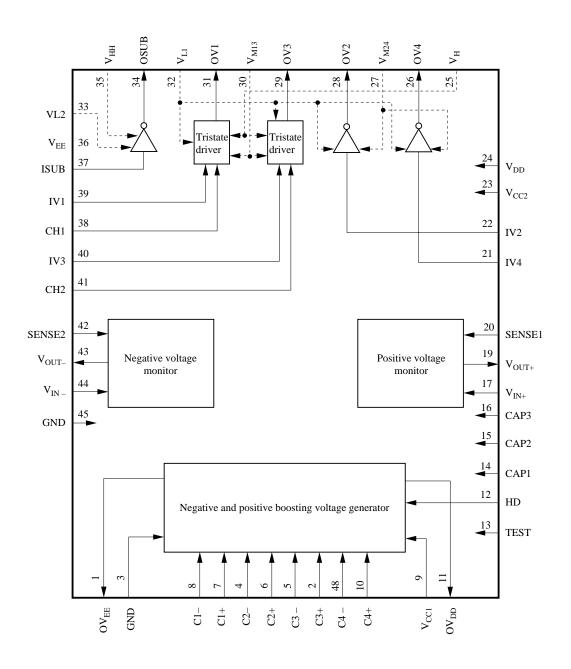
Features

- Single 5 volt power supply
- Applications
- Video cameras

■ Pin Assignment



■ Block Diagram



■ Pin Descriptions

Pin No.	Symbol	Pin Name	I/O	Function Description
9	V _{CC1}	"H" level power supply	I	"H" level input for 5 volt circuits
23	V_{CC2}	for input block		
3	GND	"L" level power supply	I	"L" level input for 5 volt circuits
45		for input block		
25	V_{H}	"H" level power supply	I	"H" level input for high-voltage circuits
		for vertical driver		
35	V_{HH}	"H" level power supply	I	"H" level input for high-voltage circuits
		for SUB driver		
30	V_{M13}	"M" level power supply	I	"M" level input for high-voltage circuits
27	V_{M24}	for vertical driver		
32	V_{L1}	"L" level power supply	I	"L" level input for high-voltage circuits
		for vertical driver		
33	V_{L2}	"L" level power supply	I	"L" level input for high-voltage circuits
		for SUB driver		
24	V_{DD}	Driver power supply 1	I	"H" level for high-voltage circuits
36	V_{EE}	Driver power supply 2	I	"L" level for high-voltage circuits
17	V_{IN+}	Voltage input for positive	I	Voltage input pin for positive voltage
		voltage monitor		monitor
44	V _{IN} –	Voltage input for negative	I	Voltage input pin for negative voltage
		voltage monitor		monitor
13	TEST	Test input	I	Test pin (Keep this pin at "H" level.)
12	HD	HD pulse input	I	HD pulse input pin
22	IV2	Transfer pulse input	I	Charge transfer pulse input pin
21	IV4	Transfer pulse input	I	Charge transfer pulse input pin
39	IV1	Transfer pulse input	I	Charge transfer pulse input pin
40	IV3	Transfer pulse input	I	Charge transfer pulse input pin
38	CH1	Charge pulse input	I	Charge readout pulse input pin
41	CH2	Charge pulse input	I	Charge readout pulse input pin
37	ISUB	SUB pulse input	I	Unwanted charge rejection pulse input pin
20	SENSE1	Positive voltage monitor	I	Positive voltage monitor control sensing
		sensing input		pin (Leave this pin open.)
42	SENSE2	Negative voltage monitor	I	Negative voltage monitor control sensing
		sensing input		pin (Leave this pin open.)
7	C1+	C1 connection	О	Booster block voltage charging capacitor
8	C1-			connection pins
6	C2+	C2 connection	О	Booster block voltage charging capacitor
4	C2-			connection pins
2	C3+	C3 connection	О	Booster block voltage charging capacitor
5	C3 –			connection pins
10	C4+	C4 connection	О	Booster block voltage charging capacitor
48	C4 –			connection pins

3

■ Pin Descriptions (continued)

Pin No.	Symbol	Pin Name	I/O	Function Description
11	OV_{DD}	Booster block positive	О	Booster block positive voltage
		voltage output		output pin
1	OV_{EE}	Booster block negative	0	Booster block negative voltage
		voltage output		output pin
19	V _{OUT+}	Positive regulated voltage	0	Positive voltage monitor output pin
		output		(Leave this pin open.)
43	V _{OUT} -	Negative regulated voltage	0	Negative voltage monitor output pin
		output		(Leave this pin open.)
26	OV4	Binary transfer pulse	0	Binary (V _{M24} , V _{L1}) transfer pulse
		output		output pin
28	OV2	Binary transfer pulse	0	Binary (V _{M24} , V _{L1}) transfer pulse
		output		output pin
29	OV3	Tristate transfer pulse	0	Tristate (V _H , V _{M13} , V _{L1}) transfer pulse
		output		output pin
31	OV1	Tristate transfer pulse	0	Tristate (V _H , V _{M13} , V _{L1}) transfer pulse
		output		output pin
34	OSUB	SUB pulse output	0	Unwanted charge (V _{HH} , V _{L2}) rejection
				pulse input pin
14	CAP1	Stabilizing capacitor	0	Pins for connecting capacitors for internal
15	CAP2	connection		voltage stabilization circuits
16	CAP3			
18	N.C.	No connection	_	
46				
47				

■ Functional Description

Binary transfer pulses (vertical driver block)

IV2	OV2
IV4	OV4
Н	L
L	M

Tristate transfer pulses (vertical driver block)

CH1	IV1	OV1
CH2	IV3	OV3
Н	Н	L
п	L	M
т	Н	L
L	L	Н

^{*1} IV1, IV2, IV3, IV4, CH1, CH2

H: V_{CC}

L: GND

OV1, OV2, OV3, OV4

H: V_H

M: V_{M13} , or V_{M24}

L: V_{L1}

Unwanted charge rejection pulses (SUB driver block)

ISUB	OSUB
Н	L
L	Н

^{*1} ISUB

H: V_{CC}

L: GND

OSUB

 $H{:}\ V_{HH}$

 $L \colon V_{L2}$

■ Electrical Characteristics

(1) DC characteristics

 $V_{HH}\!\!=\!\!V_{H}\!\!=\!\!15.0V,\,V_{M13}\!\!=\!\!V_{M24}\!\!=\!\!1.0V,\,GND\!\!=\!\!0.0V,$

 $V_{CC1} \!\!=\!\! V_{CC2} \!\!=\!\! 5.0V \; (=\!\! V_{CC}), \; V_{L1} \!\!=\!\! -7.0V, \; V_{L2} \!\!=\!\! -10.0V, \; Ta \!\!=\!\! +25^{\circ}C$

Parameter	Symbol	Test conditions	min	typ	max	Unit	
Quiescent supply current	I_{DDST}	V_{I} =GND, V_{CC}			4	mA	
Operating supply current	I _{DDDYN}	V_{I} =GND, V_{CC}			11	mA	
Power supply output pins OV_{DD} , OV_{EE}							
Positive voltage stabilization	V _{REG+}	V _I =GND, V _{CC} , I _O =7mA	14.5	15.0	15.5	V	
circuit output voltage							
Negative voltage stabilization	V _{REG} -	V _I =GND, V _{CC} , I _O =-2mA	-10.5	-10.0	-9.5	V	
circuit output voltage							
Input pins	IV1	, IV2, IV3, IV4, CH1, CH2, ISUB, H	D				
"H" level voltage	V _{IH}		3.5		V _{CC}	V	
"L" level voltage	V _{IL}		GND		1.5	V	
Input leak current	I_{LI}	V _I =0 to 5V			±1	μΑ	
Output pins 1 (Binary output) OV:	2, OV4					
Output voltage "M" level	V _{OM1}	V _I =GND, V _{CC} , I _{OM1} =-1mA	0.9		V _{M24}	V	
Output voltage "L" level	V _{OL1}	V _I =GND, V _{CC} , I _{OL1} =1mA	V_{L1}		-6.9	V	
Output on resistance "M" level	R _{ONM1}	I _{OM1} =-50mA			40	Ω	
Output on resistance "L" level	R _{ONL1}	I _{OL1} =50mA			40	Ω	
Output pins 2 (Tristate output	ıt) OV	1, OV3					
Output voltage "H" level	V _{OH2}	V_{I} =GND, V_{CC} , I_{OH2} = -1mA	14.9		V _H	V	
Output voltage "M" level	V _{OM2}	V _I =GND, V _{CC} , I _{OM2} =-1mA	0.9		V _{M13}	V	
Output voltage "L" level	V _{OL2}	V _I =GND, V _{CC} , I _{OL2} =1mA	V_{L1}		-6.9	V	
Output on resistance "H" level	R _{ONH2}	I _{OH2} =-50mA			50	Ω	
Output on resistance "M" level	R _{ONM2}	I _{OM2} =±50mA			40	Ω	
Output on resistance "L" level	R _{ONL2}	I _{OL2} =50mA			40	Ω	
Output pin 3 (SUB output) OSUB							
Output voltage "H" level	V _{OHH3}	V _I =GND, V _{CC} , I _{OHH3} =-1mA	14.9		V _{HH}	V	
Output voltage "L" level	V _{OL3}	V _I =GND, V _{CC} , I _{OL3} =1mA	V_{L2}		-9.9	V	
Output on resistance "H" level	R _{ONHH3}	I _{ONHH3} =-50mA			50	Ω	
Output on resistance "L" level	R _{ONL3}	I _{ONL3} =50mA			40	Ω	

(2) AC characteristics

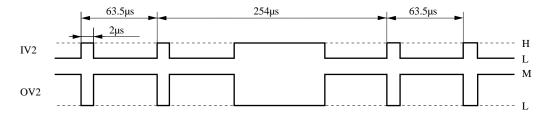
 $V_{HH}\!\!=\!\!V_{H}\!\!=\!\!15.0V,\,V_{M13}\!\!=\!\!V_{M24}\!\!=\!\!1.0V,\,GND\!\!=\!\!0.0V,$

 $V_{CC1} = V_{CC2} = 5.0V (=V_{CC}), V_{L1} = -7.0V, V_{L2} = -10.0V, Ta = +25^{\circ}C$

Parameter	Symbol	Test conditions	min	typ	max	Unit
Output pins 1 (Binary output) OV2, OV4						
Transmission delay	t _{PLM}	No load		100	200	
	t _{PML}	From "L" level to "M" level		100	200	ns
Rise time	t _{TLM}			200	300	
Fall time	t _{TML}			200	300	ns
Output pins 2 (Tristate output	it) OV	1, OV3				
Transmission delay	t _{PLM}	No load		100	200	
	t _{PML}	From "L" level to "M" level		100	200	ns
Transmission delay	t _{PMH}	No load		200	400	m.c.
	t _{PHM}	From "M" level to "H" level		200	400	ns
Rise time	t _{TLM}			200	300	nc
Fall time	t _{TML}			200	300	ns
Rise time	t _{TMH}			200	300	ne
Fall time	t _{THM}			200	300	ns
Output pin 3 (SUB output)	OSI	UB				
Transmission delay	t _{PLHH}	No load		100	200	
	t _{PHHL}	From "L" level to "H" level		100	200	ns
Rise time	t _{TLHH}			200	300	ne
Fall time	t _{THHL}			200	300	ns

■ Timing Chart

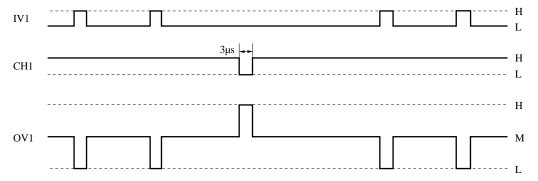
1. Binary transfer pulses



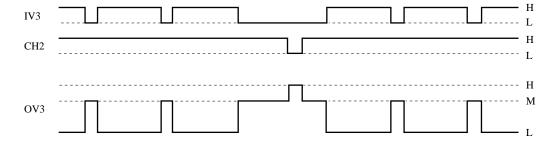
2. Binary transfer pulses



3. Tristate transfer pulses



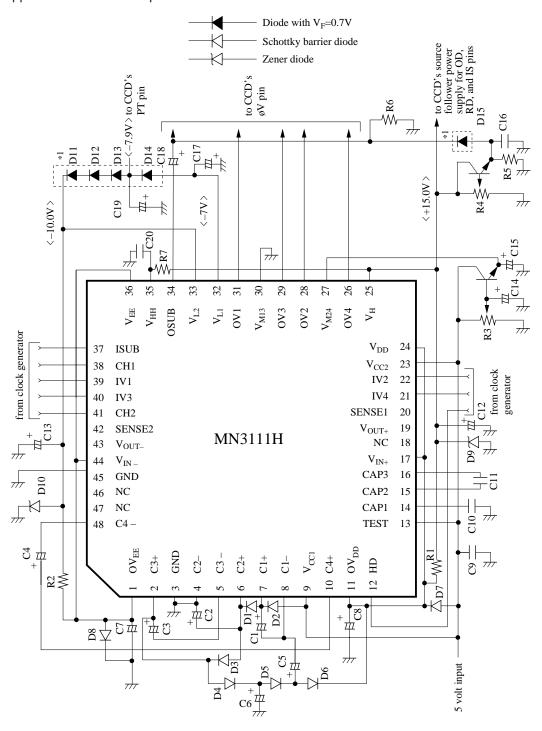
4. Tristate transfer pulses



5. SUB pulses



■ Application Circuit Example

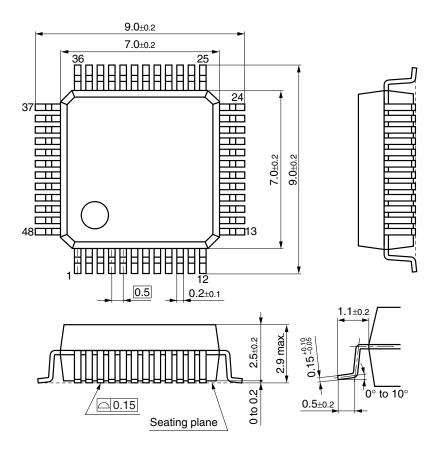


The booster circuit's electrolytic capacitors must have little impedance fluctuation at low temperatures.

Note *1: These diodes must have a V_F of 0.7 V. All other diodes, except the Zener diodes, must be Schottky barrier diodes (MA723).

■ Package Dimensions (Unit: mm)

QFH048-P-0707



Note) The package of this product will be changed to lead-free type (QFH048-P-0707B). See the new package dimensions section later of this datasheet.

Usage Notes

External components

1. This product requires eight Schottky barrier diodes and two Zener diodes.

We recommend the following components.

Schottky barrier diodes: MA723 or equivalents

Zener diodes: MA1150-M, MA8150-M (for positive regulated voltage) or equivalents

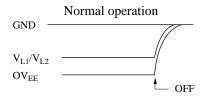
MA1100-M, MA8100-M (for negative regulated voltage) or equivalents

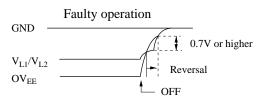
Ta=25°C

Component	Model number	Typical characteristics	Notes	
Schottky barrier diodes	MA723	$I_F = 200 \text{mA}, \ V_F \le 0.55 \text{V}$		
	MA1150-M	I 5 A 14 (N 2 N 2 15 25 N	for positive	
Zener diodes	MA8150-M	$I_Z = 5 \text{mA}, 14.6 \text{V} \le V_Z \le 15.35 \text{V}$	regulated voltage	
Zener diodes	MA1100-M	I 5 A 0.75 V < 10.25 V	for negative	
	MA8100-M	$I_Z = 5mA, 9.75V \le V_Z \le 10.25V$	regulated voltage	

The MN3111H will not operate properly if the components do not satisfy the above specifications.

2. Always use the specified components for peripheral circuits so as to ensure that OV_{EE} and V_L do not reverse potentials when the power is turned off.



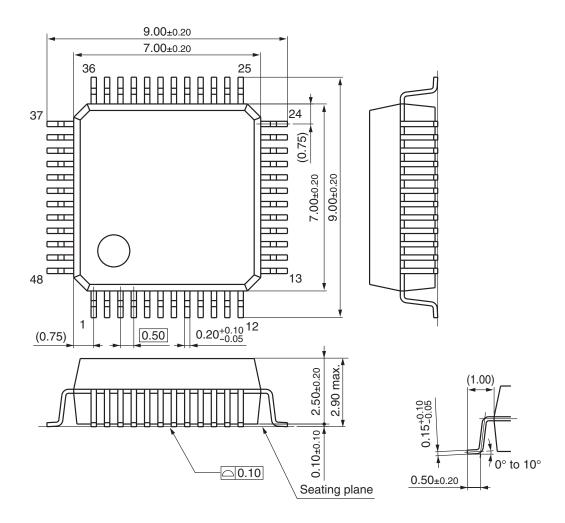


As the above sketch illustrates, allowing OV_{EE} to exceed V_{L1} and V_{L2} by more than 0.7 V produces the risk of applying a forward bias to the PN junction, turning on the parasitic transistor, and generating an overcurrent that produces latch-up.

If this phenomenon arises, increase the size of capacitor C7 or decrease the size of capacitor C13 to increase the OV_{EE} time constant.

(See the sample application circuit for the locations of C7 and C13.)

- New Package Dimensions (Unit: mm)
- QFH048-P-0707B (Lead-free package)



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